Please cancel claims 32 and 43 and amend claims 29 and 40 as follows:

## CLAIMS (Complete set)

- 1 28. (canceled)
- 29. (currently amended) A die, comprising:
- a first conductor carrying a power supply voltage;
- a second conductor carrying a ground voltage; and
- a semiconductor decoupling capacitor to provide decoupling capacitance between the first and second conductors, the semiconductor decoupling capacitor including:
  - (a) a gate electrode coupled to the first conductor to receive the power supply voltage,
  - (b) a diffusion coupled to the second conductor to receive the ground voltage, and
  - (c) a body to receive the ground voltage through the diffusion, the semiconductor decoupling capacitor thereby being in depletion mode[[.]];

wherein the diffusion is a first diffusion and the semiconductor decoupling capacitor further includes a second diffusion coupled to the second conductor to receive the ground voltage and wherein the body receives the ground voltage through the first and second diffusions.

- 30. (previously presented) The die of claim 29, wherein gate electrode is p-type and the diffusion and the body are n-type.
- 31. (previously presented) The die of claim 29, wherein gate electrode is p-type and the diffusion and the body are n-type, with the diffusion being more heavily doped than the body.
  - 32. (Canceled)
- 33. (previously presented) The die of claim 32, wherein the first and second diffusions are source/drain diffusions.
- 34. (Previously presented) The die of claim 32, wherein the first and second diffusions are more heavily doped than the body.
- 35. (previously presented) The die of claim 29, wherein the semiconductor decoupling capacitor has a flatband voltage and wherein the power supply voltage has a smaller absolute value than does the flatband voltage.
- 36. (previously presented) The die of claim 29, wherein gate electrode is p-type and the diffusion and the body are n-type, and wherein the diffusion is a body tap diffusion and the semiconductor decoupling capacitor further includes first and second source/drain diffusions that

are p-type.

- 37. (previously presented) The die of claim 36, wherein the first and second source/drain diffusions are coupled to the second conductor to receive the ground voltage.
- 38. (previously presented) The die of claim 36, wherein the body tap diffusion and first and second source/drain diffusions are more heavily doped than the body.
- 39. (previously presented) The die of claim 36, wherein the semiconductor decoupling capacitor has a flatband voltage and wherein the power supply voltage has a smaller absolute value than does the flatband voltage.
  - 40. (Currently amended) A die, comprising:
  - a first conductor carrying a power supply voltage;
  - a second conductor carrying a ground voltage; and
- a semiconductor decoupling capacitor to provide decoupling capacitance between the first and second conductors, the semiconductor decoupling capacitor including:
  - (a) a gate electrode coupled to the second conductor to receive the ground voltage,
  - (b) a diffusion coupled to the first conductor to receive the power supply voltage,
  - (c) a body to receive the power supply voltage through the diffusion, the semiconductor decoupling capacitor thereby being in depletion mode,
  - (d) a substrate, and
  - (e) an insulation between the substrate and the body[[.]];

wherein the diffusion is a first diffusion and the semiconductor decoupling capacitor further includes a second diffusion coupled to the first conductor to receive the power supply voltage and wherein the body receives the power supply voltage through the first and second diffusions.

- 41. (previously presented) The die of claim 40, wherein gate electrode is n-type and the diffusion and the body are p-type.
- 42. (previously presented) The die of claim 40, wherein gate electrode is n-type and the diffusion and the body are p-type, with the diffusion being more heavily doped than the body.
  - 43. (Canceled)
- 44. (previously presented) The die of claim 43, wherein the first and second diffusions are source/drain diffusions.

- 45. (Previously presented) The die of claim 43, wherein the first and second diffusions are more heavily doped than the body.
- 46. (previously presented) The die of claim 40, wherein the semiconductor decoupling capacitor has a flatband voltage and wherein the power supply voltage has a smaller absolute value than does the flatband voltage.
- 47. (previously presented) The die of claim 40, wherein gate electrode is n-type and the diffusion and the body are p-type, and wherein the diffusion is a body tap diffusion and the semiconductor decoupling capacitor further includes first and second source/drain diffusions that are n-type.
- 48. (previously presented) The die of claim 47, wherein the first and second source/drain diffusions are coupled to the second conductor to receive the ground voltage.
- 49. (previously presented) The die of claim 47, wherein the body tap diffusion and first and second source/drain diffusions are more heavily doped than the body.
- 50. (previously presented) The die of claim 47, wherein the semiconductor decoupling capacitor has a flatband voltage and wherein the power supply voltage has a smaller absolute value than does the flatband voltage.